



**BOND
UNIVERSITY**
BRINGING AMBITION TO LIFE

Bond University 2012 Alumni Scholarship

Information Pack and Application Form



BOND UNIVERSITY ALUMNI SCHOLARSHIP

Bond University is proud to launch the inaugural Bond University Alumni Scholarship.

Made possible by the support of alumni donations from the 2011 Annual Fund, the Scholarship assists outstanding Bond University alumni by providing financial support enabling them to undertake postgraduate study at the world's finest universities, appropriate to their field of study. The approved list of universities at which study can be undertaken are detailed below.

VALUE

Up to two scholarships will be awarded in 2012, valued at \$20,000 each. The Scholarship can be utilised for tuition fees at the nominated institution, as well as any associated travel and accommodation costs directly related to undertaking the study program.

APPROVED INSTITUTIONS

Applicants who have been accepted, or have sought application to study at any of the following institutions may be eligible to apply for the Scholarship.

- California Institute of Technology, United States
- Columbia University, United States
- Dartmouth College, United States
- Harvard University, United States
- Imperial College London, United Kingdom
- Massachusetts Institute of Technology, United States
- Princeton University, United States
- Stanford University, United States
- University of California, Berkeley, United States
- University of Cambridge, United Kingdom
- University of Chicago, United States
- University of Oxford, United Kingdom
- Yale University, United States

Applications for the Scholarship can be submitted prior to acceptance at any of the above listed institutions, however final proof of acceptance must be provided prior to the close of applications.



SELECTION CRITERIA

To be awarded the Bond University Alumni Scholarship, applicants must be a graduate of Bond University or a current student in their final year of study at Bond University. Both Australian and international, undergraduate and postgraduate students and alumni are eligible. Other factors considered include:

- Academic merit
- Demonstrated and / or potential leadership
- Citizenship and community service
- Demonstrated commitment to study
- Referee reports outlining the applicant's abilities

Academic field of study does not limit the scholarship.

Applicants currently enrolled in one of the approved institutions, with at least half of their degree remaining, are eligible to apply.

The recipient shall not hold any other scholarship or award at the host university concurrently with the Bond University Alumni Scholarship, except with the permission of Bond University. Late applications will not be accepted.

Successful applicants are required to submit a report each year during their studies abroad and upon completion. The report will provide a general overview of the applicant's ongoing study experience at the host institution, as well as detailing how the funds have been used. Any unused portion of the scholarship will be returned to the University with their completion report.

APPLICATION AND SELECTION

Applicants must complete the Bond University Alumni Scholarship application form and submit a personal statement.

Applicants must also provide a curriculum vitae and academic transcript from all tertiary education within the past five years.

A final round telephone interview may also be necessary.

Application Dates

Applications open: February 6, 2012

Applications close: April 30, 2012

Successful applicants will be notified by May 31, 2012.

The Alumni Relations Office will shortlist applicants and recommend nominations for consideration by the Selection Panel, which will consist of:

- Deputy Vice-Chancellor and Provost
- Pro Vice-Chancellor (Students & Academic Support)
- Director of Development & External Relations

Winners of the Bond University Alumni Scholarship will be informed by the Director of Development & External Relations and will be publically announced by the Office of Development & External Relations.

APPLICATION FORM

SECTION 1

PERSONAL AND CONTACT DETAILS

Applicant's name (as shown on your passport)

Title	Given name(s)

Surname or family name

Date of birth	Citizenship

Mailing Address

Number and street

Suburb / town	State / province	Postcode	Country

Permanent address in home country (if different to above)

Number and street

Suburb / town	State / province	Postcode	Country

SECTION 2

EDUCATION AND EMPLOYMENT RECORD

Bond University qualifications	Year / semester started (e.g. 081)	Year / semester finished (e.g. 081)

Other qualifications (Please note degree and institution)	Year started	Year finished

NOMINEE'S PROFESSIONAL DETAILS

Current employer

Industry

Position (exact title)	Year appointed

SECTION 3**FINANCIAL INFORMATION**

Annual income

Are you currently the recipient of any other scholarship or award?

Yes (Please provide details below)

No

SECTION 4**INSTITUTION AND COMMENCEMENT DATES**

Have you been accepted to any of the institutions on the approved list?

Yes (Go to section 4a)

No (Go to section 4b)

Section 4a

Name of institution and postgraduate study program you have been accepted into. Please attach to application proof of institutional acceptance.

Institution

Study program

When will you be starting the above nominated study program?

Semester number

Year

Section 4b

Name of institution(s) and postgraduate study program(s) you have sought or will seek acceptance. Please note proof of institutional acceptance will need to be provided prior to the close of applications.

> Preference 1

Institution

Study program

If accepted, when would you be starting the above nominated study program?

Semester number

Year

> Preference 2

Institution

Study program

If accepted, when would you be starting the above nominated study program?

Semester number

Year

> Preference 3

Institution

Study program

If accepted, when would you be starting the above nominated study program?

Semester number

Year

SECTION 5

PERSONAL STATEMENT

Attach a personal statement (no more than one A4 page) about yourself, addressing your eligibility based on the criteria and the benefits you will receive if awarded a scholarship. As a guide, you might focus on the following:

- How will the Bond University Alumni Scholarship benefit you?
- Why have you chosen the nominated institution(s) and study program(s)?
- How do you envisage the nominated institution(s) and study program(s) assisting you in the future?

SECTION 6**CURRICULUM VITAE**

Please attach a current curriculum vitae. Please ensure this contains academic qualifications (including qualifications awarded to you by other educational institutions), a summary of your career since graduation and professional referees.

SECTION 7**ACADEMIC TRANSCRIPT**

Please attach academic transcripts from all tertiary education within the past five years.

SECTION 8**CHECKLIST AND DECLARATION**

Have you provided the following, including all relevant documentation?

- Application form (pages 4 to 7)
- Personal statement
- Current curriculum vitae
- Academic transcripts (from all tertiary education within the past five years)
- Proof of institutional acceptance (if already accepted)

 Yes

I wish to apply for a Bond University Alumni Scholarship and declare the information I have given in the application is true and correct. I understand that Bond University reserves the right to vary or reverse any decision made on the basis of incorrect or incomplete information.

Applicant's name

Applicant's signature (if returning by post)

Applicant's signature (if returning online)

By ticking the AGREE box to the right I agree that I am attaching my e-signature which I acknowledge and agree is the legal equivalent of submitting a document signed by hand.

Date

<input type="text"/>	<input type="text"/>	<input type="text"/>
Day	Month	Year

SUBMISSION DETAILS

Applications can be submitted via one of the options below.

Email: alumni@bond.edu.au

Fax: +61 7 5595 5752

Post: Alumni Relations Office

Office of Development & External Relations
Bond University Queensland 4229
Australia